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<p>1. Name of conveying party(ies):</p> <p>In-Kil PARK Duk-Hee LEE</p> <p><i>05/02/01</i></p>	<p>2. Name and address of receiving party(ies):</p> <p>Innochips Technology 5F., 248-14, Eunhang-Dong Shiheung-Si, Kyungki-do 429-060 Rep. of Korea</p>
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jc862 U.S. PTO
09/847782
05/02/01

Additional name(s) of conveying party(ies) attached? Yes No

Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance:

Assignment Merger
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Execution Date: April 16, 2001

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s) *09/847782* B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed: 6. Total number of applications and patents involved: 1

Name: Curtis B. Hamre
Address: Merchant & Gould P.C.
P.O. Box 2903
Minneapolis, MN 55402-0903



7. Total fee (37 CFR 3.41): \$40.00
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PATENT
REEL: 011781 FRAME: 0083

ASSIGNMENT

INSTRUCTIONS

WHEREAS, We, In-Kil Park and Duk-Hee Lee having a Post Office Address at 5F., 248-14, Eunhang-Dong, Shiheung-Si, Kyungki-Do, 429-060, Rep. of Korea

Date Patent Declaration Signed and Title Serial No. and filing date (if known)

(herein called "THE UNDERSIGNED") have made an invention and have executed an application for Letters Patent of the United States on even date herewith for this invention, which application is entitled

LOW INDUCTANCE MULTILAYER CHIP AND METHOD FOR FABRICATING SAME

And which has been given Serial Number _____ and the filing date of _____;

Name of assignee

WHEREAS Innochips Technology (herein called "ASSIGNEE"), whose post address is 5F., 248-14, Eunhang-Dong, Shiheung-Si, Kyungki-Do, 429-060, Rep. of Korea

State or Country of Incorporation and Address

Wishes to acquire the entire right, title and interest in and to said invention and patent application and any Letters Patent to be obtained therefor;

NOW, THEREFORE, for and in consideration of the sum of One Dollar and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, THE UNDERSIGNED hereby sell, assign and transfer to the ASSIGNEE, its successors and assigns, the entire right, title and interest for the United States in and to the invention disclosed in the aforesaid application, and in and to the said application, all divisions, continuations, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and THE UNDERSIGNED hereby authorize and request the Commissioner of Patents to issue any and all United States Letters Patent for the aforesaid invention to the ASSIGNEE of the entire right, title and interest in and to the same, for the use of the ASSIGNEE, its successors and assigns.

THE UNDERSIGNED hereby agree that THE UNDERSIGNED, their executors and legal representatives will make, execute and deliver (without charge but at the expense of the ASSIGNEE) any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said ASSIGNEE, its successors and representatives all facts known to THE UNDERSIGNED relating to said invention and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable to vest the ASSIGNEE, its successors or assigns the entire right, title and interest in and to the said invention, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

THE UNDERSIGNED represent and agree with said ASSIGNEE its successors and assigns, that no assignment grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by THE UNDERSIGNED, and that full right to convey the same as herein expressed is possessed by THE UNDERSIGNED.

IN TESTIMONY WHEREOF, THE UNDERSIGNED have hereunto set their hand on the dates indicated below.

Each inventor must sign &
date



Signature In-Kil Park

16th. Apr. 2001

Date

Note: No legalization or
other



Signature Duk-Mee Kim

16th. Apr. 2001

Date

witness required